

**APPENDIX A**  
**"CLEAN" VERSION OF EACH PARAGRAPH/SECTION/CLAIM**  
**37 C.F.R. § 1.121(b)(ii) AND (c)(i)**

**SPECIFICATION:**

Paragraph at page 3, line 20, to line 24:

Figure 3 and 4 show the die 10 of Figures 1 and 2 where a thin, flexible adhesive film 13 is used to bond the die 10 and substrate 12. Film 13 is electrically conductive or may be insulative, and is heat curable. The use of such film is seen in Figures 2 and 4 to eliminate overspill, thus enabling a larger area die 10 on the substrate 11 of same area as that of Figures 1 and 2.

**CLAIMS (with indication of amended or new):**

1. (Amended) A process of connecting semiconductor die to a substrate having a top surface, said process comprising the steps of:

providing a thin, flexible, heat curable film which is of a first area;

placing said thin flexible film on a thin semiconductor wafer of a second area, said semiconductor wafer being provided with a plurality of spaced apart semiconductor die, each of said semiconductor die having a respective third area which is substantially less than said first area;

preheating said semiconductor wafer and said thin flexible film to partially cure said thin flexible film, thereby forming adhesion between said thin flexible film and said semiconductor wafer;

thereafter simultaneously singulating both said thin flexible film and said plurality of identical semiconductor die to form individual elements;

thereafter applying at least one of said singulated semiconductor to the top surface of said substrate surface with the thin flexible film on said die pressed against said top surface and adhered thereto; and

thereafter heating said one semiconductor die to fully cure said thin flexible film to firmly adhere said die to said substrate.